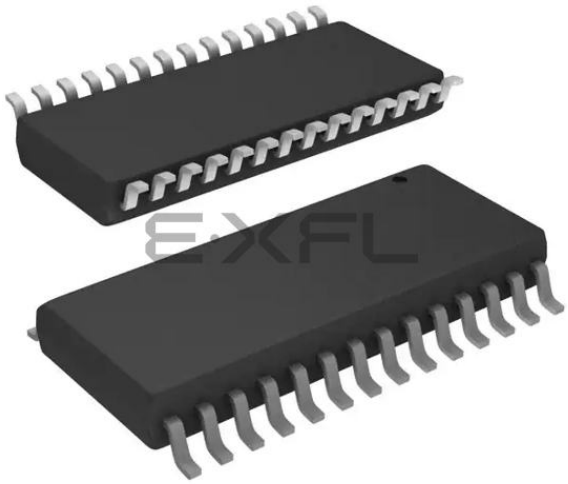

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c66-04i-so

TABLE 3-1: PIC16C61 PINOUT DESCRIPTION

Pin Name	DIP Pin#	SOIC Pin#	Pin Type	Buffer Type	Description
OSC1/CLKIN	16	16	I	ST/CMOS(1)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	4	4	I/P	ST	Master clear reset input or programming voltage input. This pin is an active low reset to the device.
					PORTA is a bi-directional I/O port.
RA0	17	17	I/O	TTL	
RA1	18	18	I/O	TTL	
RA2	1	1	I/O	TTL	
RA3	2	2	I/O	TTL	
RA4/T0CKI	3	3	I/O	ST	RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.
					PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	6	6	I/O	TTL/ST(2)	RB0 can also be the external interrupt pin.
RB1	7	7	I/O	TTL	
RB2	8	8	I/O	TTL	
RB3	9	9	I/O	TTL	
RB4	10	10	I/O	TTL	Interrupt on change pin.
RB5	11	11	I/O	TTL	Interrupt on change pin.
RB6	12	12	I/O	TTL/ST(3)	Interrupt on change pin. Serial programming clock.
RB7	13	13	I/O	TTL/ST(3)	Interrupt on change pin. Serial programming data.
VSS	5	5	P	—	Ground reference for logic and I/O pins.
VDD	14	14	P	—	Positive supply for logic and I/O pins.

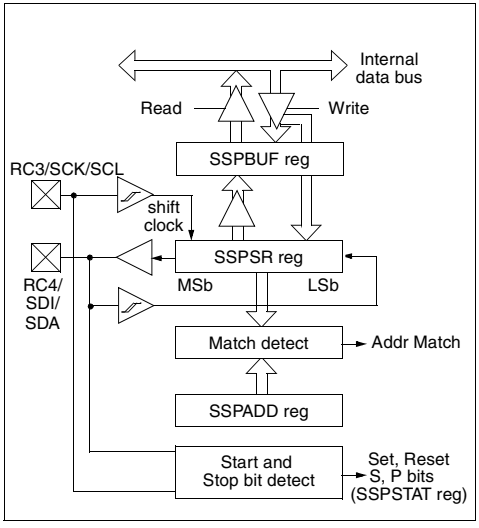
Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.
2: This buffer is a Schmitt Trigger input when configured as the external interrupt.
3: This buffer is a Schmitt Trigger input when used in serial programming mode.

11.5 SSP I²C Operation

The SSP module in I²C mode fully implements all slave functions, except general call support, and provides interrupts on start and stop bits in hardware to facilitate firmware implementations of the master functions. The SSP module implements the standard mode specifications as well as 7-bit and 10-bit addressing. Two pins are used for data transfer. These are the RC3/SCK/SCL pin, which is the clock (SCL), and the RC4/SDI/SDA pin, which is the data (SDA). The user must configure these pins as inputs or outputs through the TRISC<4:3> bits. The SSP module functions are enabled by setting SSP Enable bit SSPEN (SSPCON<5>).

FIGURE 11-24: SSP BLOCK DIAGRAM (I²C MODE)



The SSP module has five registers for I²C operation. These are the:

- SSP Control Register (SSPCON)
- SSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer (SSPBUF)
- SSP Shift Register (SSPSR) - Not directly accessible
- SSP Address Register (SSPADD)

The SSPCON register allows control of the I²C operation. Four mode selection bits (SSPCON<3:0>) allow one of the following I²C modes to be selected:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- I²C Slave mode (7-bit address), with start and stop bit interrupts enabled
- I²C Slave mode (10-bit address), with start and stop bit interrupts enabled
- I²C Firmware controlled Master Mode, slave is idle

Selection of any I²C mode, with the SSPEN bit set, forces the SCL and SDA pins to be open drain, provided these pins are programmed to inputs by setting the appropriate TRISC bits.

The SSPSTAT register gives the status of the data transfer. This information includes detection of a START or STOP bit, specifies if the received byte was data or address if the next byte is the completion of 10-bit address, and if this will be a read or write data transfer. The SSPSTAT register is read only.

The SSPBUF is the register to which transfer data is written to or read from. The SSPSR register shifts the data in or out of the device. In receive operations, the SSPBUF and SSPSR create a doubled buffered receiver. This allows reception of the next byte to begin before reading the last byte of received data. When the complete byte is received, it is transferred to the SSPBUF register and flag bit SSPIF is set. If another complete byte is received before the SSPBUF register is read, a receiver overflow has occurred and bit SSPOV (SSPCON<6>) is set and the byte in the SSPSR is lost.

The SSPADD register holds the slave address. In 10-bit mode, the user first needs to write the high byte of the address (`1111 0 A9 A8 0`). Following the high byte address match, the low byte of the address needs to be loaded (A7:A0).

FIGURE 12-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER (ADDRESS 18h)

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D
bit7							bit0

R	= Readable bit
W	= Writable bit
U	= Unimplemented bit, read as '0'
- n	= Value at POR reset
x	= unknown

bit 7: **SPEN**: Serial Port Enable bit
(Configures RC7/RX/DT and RC6/TX/CK pins as serial port pins when bits TRISC<7:6> are set)
1 = Serial port enabled
0 = Serial port disabled

bit 6: **RX9**: 9-bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5: **SREN**: Single Receive Enable bit

Asynchronous mode
Don't care

Synchronous mode - master
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.

Synchronous mode - slave
Unused in this mode

bit 4: **CREN**: Continuous Receive Enable bit

Asynchronous mode
1 = Enables continuous receive
0 = Disables continuous receive

Synchronous mode
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

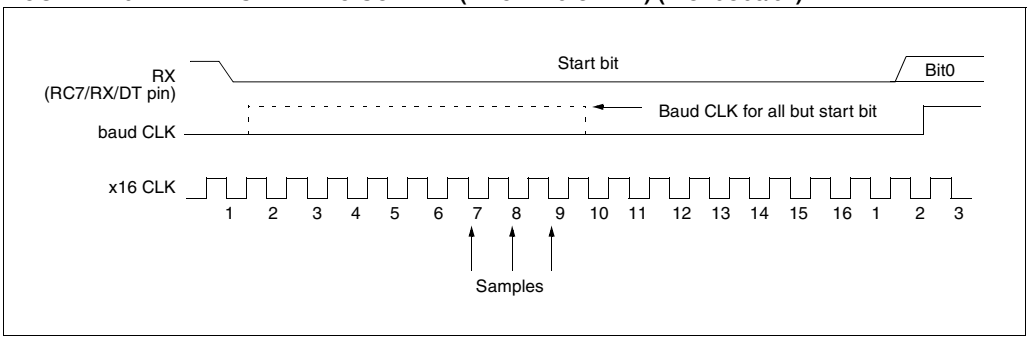
bit 3: **Unimplemented:** Read as '0'

bit 2: **FERR**: Framing Error bit
1 = Framing error (Can be updated by reading RCREG register and receive next valid byte)
0 = No framing error

bit 1: **OERR**: Overrun Error bit
1 = Overrun error (Can be cleared by clearing bit CREN)
0 = No overrun error

bit 0: **RX9D**: 9th bit of received data (Can be parity bit)

FIGURE 12-6: RX PIN SAMPLING SCHEME (BRGH = 0 OR = 1) (PIC16C66/67)



13.4.5 TIME-OUT SEQUENCE

On power-up the time-out sequence is as follows: First a PWRT time-out is invoked after the POR time delay has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode, with the PWRT disabled, there will be no time-out at all. Figure 13-11, Figure 13-12, and Figure 13-13 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if the $\overline{MCLR}$/VPP pin is kept low long enough, the time-outs will expire. Then bringing the $\overline{MCLR}$/VPP pin high will begin execution immediately (Figure 13-14). This is useful for testing purposes or to synchronize more than one PIC16CXX device operating in parallel.

Table 13-10 and Table 13-11 show the reset conditions for some special function registers, while Table 13-12 shows the reset conditions for all the registers.

13.4.6 POWER CONTROL/STATUS REGISTER (PCON)

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The Power Control/Status Register, PCON has up to two bits, depending upon the device. Bit0 is not implemented on the PIC16C62/64/65.

Bit0 is $\overline{BOR}$ (Brown-out Reset Status bit). $\overline{BOR}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{BOR}$ cleared, indicating that a brown-out has occurred. The $\overline{BOR}$ status bit is a “Don’t Care” and is not necessarily predictable if the Brown-out Reset circuitry is disabled (by clearing bit BODEN in the Configuration Word).

Bit1 is $\overline{POR}$ (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 13-5: TIME-OUT IN VARIOUS SITUATIONS, PIC16C61/62/64/65

Oscillator Configuration	Power-up		Wake-up from SLEEP
	PWRTE = 1	PWRTE = 0	
XT, HS, LP	72 ms + 1024TOSC	1024TOSC	1024 TOSC
RC	72 ms	—	—

TABLE 13-6: TIME-OUT IN VARIOUS SITUATIONS, PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67

Oscillator Configuration	Power-up		Brown-out	Wake up from SLEEP
	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1		
XT, HS, LP	72 ms + 1024TOSC	1024TOSC	72 ms + 1024TOSC	1024 TOSC
RC	72 ms	—	72 ms	—

TABLE 13-7: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C61

$\overline{TO}$	$\overline{PD}$	
1	1	Power-on Reset or $\overline{MCLR}$ reset during normal operation
0	1	WDT Reset
0	0	WDT Wake-up
1	0	$\overline{MCLR}$ reset during SLEEP or interrupt wake-up from SLEEP

TABLE 13-8: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C62/64/65

$\overline{POR}$	$\overline{TO}$	$\overline{PD}$	
0	1	1	Power-on Reset
0	0	x	Illegal, $\overline{TO}$ is set on a Power-on Reset
0	x	0	Illegal, $\overline{PD}$ is set on a Power-on Reset
1	0	1	WDT Reset
1	0	0	WDT Wake-up
1	u	u	$\overline{MCLR}$ reset during normal operation
1	1	0	$\overline{MCLR}$ reset during SLEEP or interrupt wake-up from SLEEP

Legend: x = unknown, u = unchanged

13.5.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if edge select bit INTEDG (OPTION<6>) is set, or falling, if bit INTEDG is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake the processor from SLEEP, if enable bit INTE was set prior to going into SLEEP. The status of global enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 13.8 for details on SLEEP mode.

13.5.2 TMR0 INTERRUPT

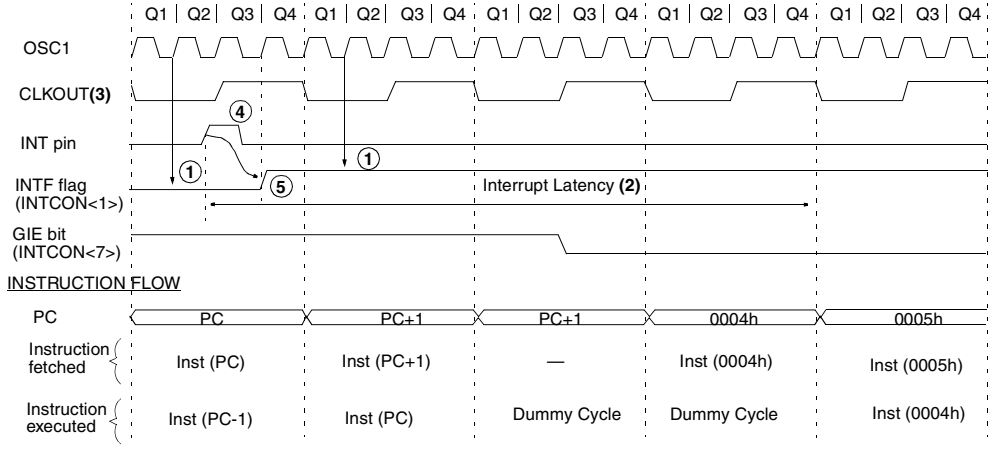
An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>) (Section 7.0).

13.5.3 PORTB INTERRUPT ON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>) (Section 5.2).

Note:	For the PIC16C61/62/64/65, if a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then flag bit RBIF may not get set.

FIGURE 13-19: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Interrupt latency = 3TCY for synchronous interrupt and 3-4TCY for asynchronous interrupt. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT is available only in RC oscillator mode.

4: For minimum width spec of INT pulse, refer to AC specs.

5: INTF can to be set anytime during the Q4-Q1 cycles.

RLF **Rotate Left f through Carry**

Syntax: [*label*] RLF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

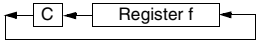
Operation: See description below

Status Affected: C

Encoding:

00	1101	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example
```
RLF     REG1,0
```
Before Instruction
```
REG1  =  1110 0110
C     =  0
```
After Instruction
```
REG1  =  1110 0110
W     =  1100 1100
C     =  1
```

RRF **Rotate Right f through Carry**

Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

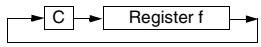
Operation: See description below

Status Affected: C

Encoding:

00	1100	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example
```
RRF     REG1,0
```
Before Instruction
```
REG1  =  1110 0110
C     =  0
```
After Instruction
```
REG1  =  1110 0110
W     =  0111 0011
C     =  0
```

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (destination)

Status Affected: C, DC, Z

Encoding:

00	0010	dfff	ffff

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example 1:
```
SUBWF   REG1,1
```
Before Instruction
```
REG1  =  3
W     =  2
C     =  ?
Z     =  ?
```
After Instruction
```
REG1  =  1
W     =  2
C     =  1; result is positive
Z     =  0
```
Example 2: Before Instruction
```
REG1  =  2
W     =  2
C     =  ?
Z     =  ?
```
After Instruction
```
REG1  =  0
W     =  2
C     =  1; result is zero
Z     =  1
```
Example 3: Before Instruction
```
REG1  =  1
W     =  2
C     =  ?
Z     =  ?
```
After Instruction
```
REG1  =  0xFF
W     =  2
C     =  0; result is negative
Z     =  0
```

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (destination<7:4>),
(f<7:4>) → (destination<3:0>)

Status Affected: None

Encoding:

00	1110	dfff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example
```
SWAPF REG,  0
```
Before Instruction
```
REG1  =  0xA5
```
After Instruction
```
REG1  =  0xA5
W     =  0x5A
```

TRIS **Load TRIS Register**

Syntax: [*label*] TRIS f

Operands: $5 \le f \le 7$

Operation: (W) → TRIS register f;

Status Affected: None

Encoding:

00	0000	0110	0fff

Description: The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PIC16CXX products, do not use this instruction.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

15.0 ELECTRICAL CHARACTERISTICS FOR PIC16C61

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55°C to +125°C

Storage temperature ..... -65°C to +150°C

Voltage on any pin with respect to VSS (except VDD, $\overline{MCLR}$, and RA4) ..... -0.3V to (VDD + 0.3V)

Voltage on VDD with respect to VSS ..... -0.3V to +7.5V

Voltage on $\overline{MCLR}$ with respect to VSS (Note 2) ..... 0V to +14V

Voltage on RA4 pin with respect to Vss ..... 0V to +14V

Total power dissipation (Note 1) ..... 800 mW

Maximum current out of VSS pin ..... 150 mA

Maximum current into VDD pin ..... 100 mA

Input clamp current, IIK (VI < 0 or VI > VDD) ..... ± 20 mA

Output clamp current, IOK (VO < 0 or VO > VDD) ..... ± 20 mA

Maximum output current sunk by any I/O pin ..... 25 mA

Maximum output current sourced by any I/O pin ..... 20 mA

Maximum current sunk by PORTA ..... 80 mA

Maximum current sourced by PORTA ..... 50 mA

Maximum current sunk by PORTB ..... 150 mA

Maximum current sourced by PORTB ..... 100 mA

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - ∑ IOH} + ∑ {(VDD-VOH) x IOH} + ∑(VOl x IOL)

Note 2: Voltage spikes below VSS at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to VSS.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 15-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C61-04	PIC16C61-20	PIC16LC61-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 μA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 μA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 μA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 μA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 μA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.0 μA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 μA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 μA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 15 μA typ. at 32 kHz, 4.0V IPD: 0.6 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 32 μA max. at 32 kHz, 3.0V IPD: 9 μA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 32 μA max. at 32 kHz, 3.0V IPD: 9 μA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 16-21: IOL VS. VOL, VDD = 3V

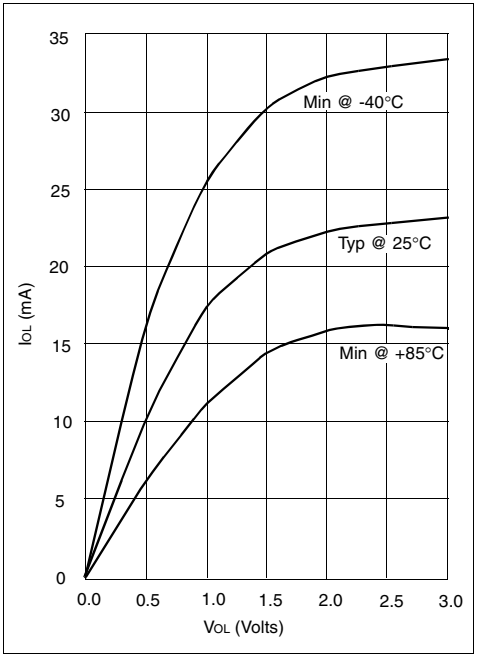


FIGURE 16-22: IOL VS. VOL, VDD = 5V

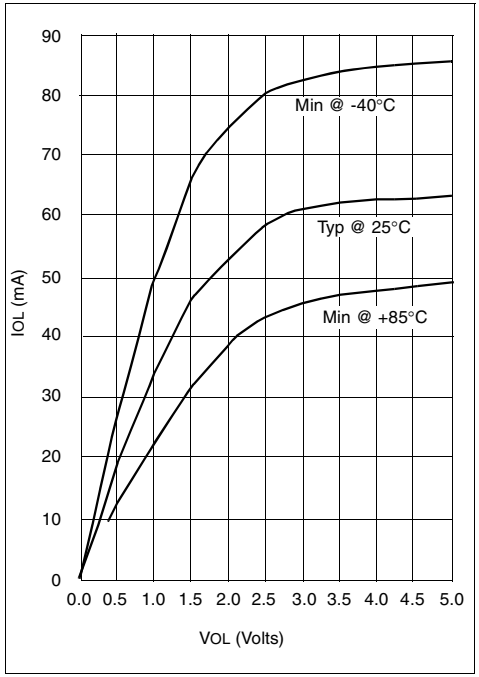


TABLE 16-2: INPUT CAPACITANCE*

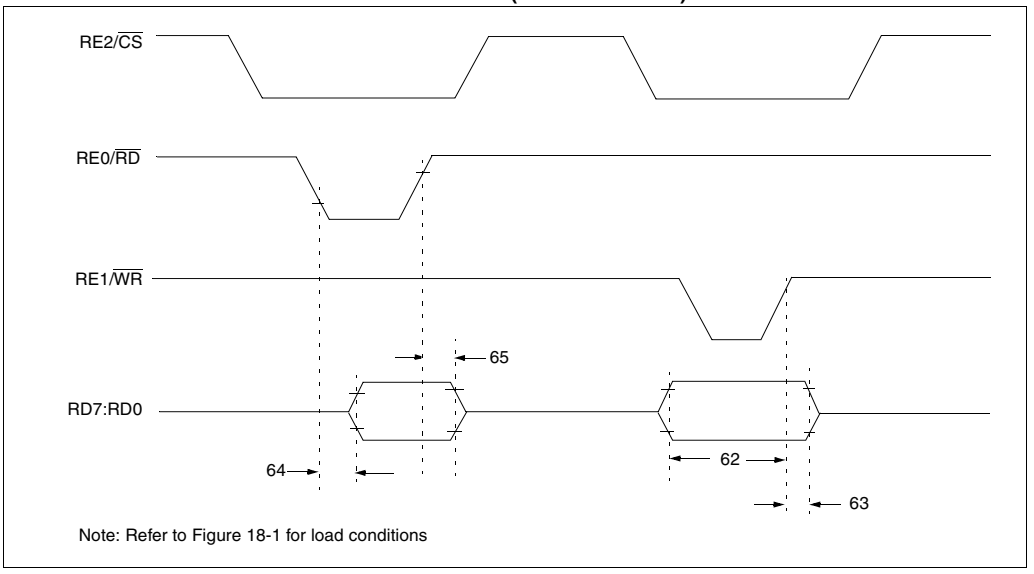
Pin Name	Typical Capacitance (pF)	
	18L PDIP	18L SOIC
RA port	5.0	4.3
RB port	5.0	4.3
$\overline{MCLR}$	17.0	17.0
OSC1/CLKIN	4.0	3.5
OSC2/CLKOUT	4.3	3.5
T0CKI	3.2	2.8

*All capacitance values are typical at 25°C. A part to part variation of ±25% (three standard deviations) should be taken into account.

Data based on matrix samples. See first page of this section for details.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 18-8: PARALLEL SLAVE PORT TIMING (PIC16C64A/R64)



Note: Refer to Figure 18-1 for load conditions

TABLE 18-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16C64A/R64)

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ (setup time)		20	—	—	ns	
				25	—	—	ns	Extended Range Only
63*	TwrH2dtI	$\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ to data–in invalid (hold time)	PIC16**C**64A/R64	20	—	—	ns	
			PIC16**LC**64A.R64	35	—	—	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid		—	—	80	ns	
				—	—	90	ns	Extended Range Only
65*	TrdH2dtI	$\overline{RD}\uparrow$ or $\overline{CS}\uparrow$ to data–out invalid		10	—	30	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

20.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I^2C specifications only)
4. Ts (I^2C specifications only)

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

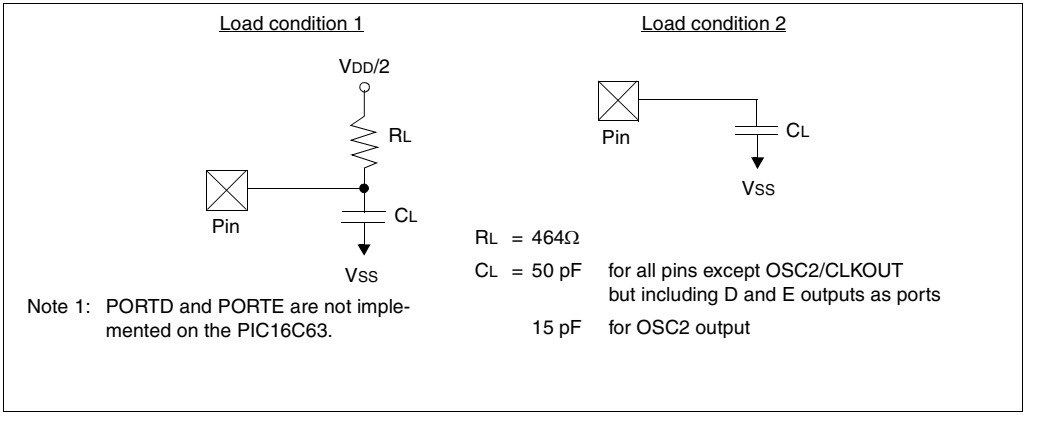
Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I^2C only			
AA	output access	High	High
BUF	Bus free	Low	Low

TCC:ST (I^2C specifications only)

CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		

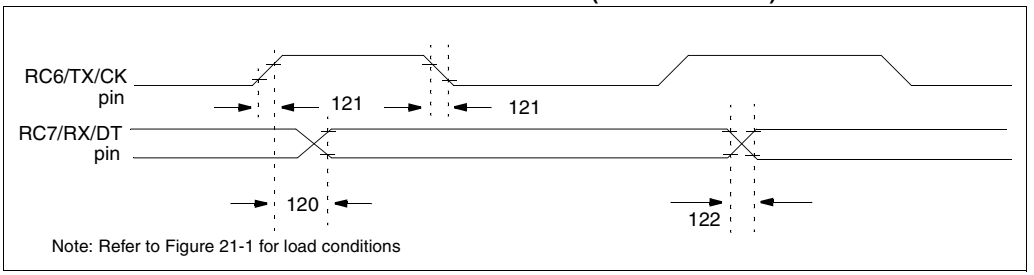
FIGURE 20-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



Note 1: PORTD and PORTE are not implemented on the PIC16C63.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 21-12: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



Note: Refer to Figure 21-1 for load conditions

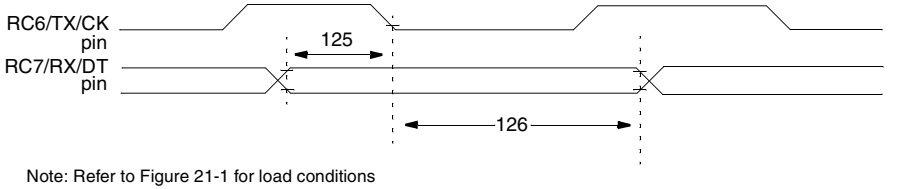
TABLE 21-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120*	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	PIC16**CR**63/R65	—	—	80	ns	
			PIC16**LCR**63/R65	—	—	100	ns	
121*	Tckrf	Clock out rise time and fall time (Master Mode)	PIC16**CR**63/R65	—	—	45	ns	
			PIC16**LCR**63/R65	—	—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16**CR**63/R65	—	—	45	ns	
			PIC16**LCR**63/R65	—	—	50	ns	

* These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 21-13: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 21-1 for load conditions

TABLE 21-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125*	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126*	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

* These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

22.2 DC Characteristics: PIC16LC66/67-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	VDD	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current (Note 3, 5)	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 22-11: SPI SLAVE MODE TIMING (CKE = 0)

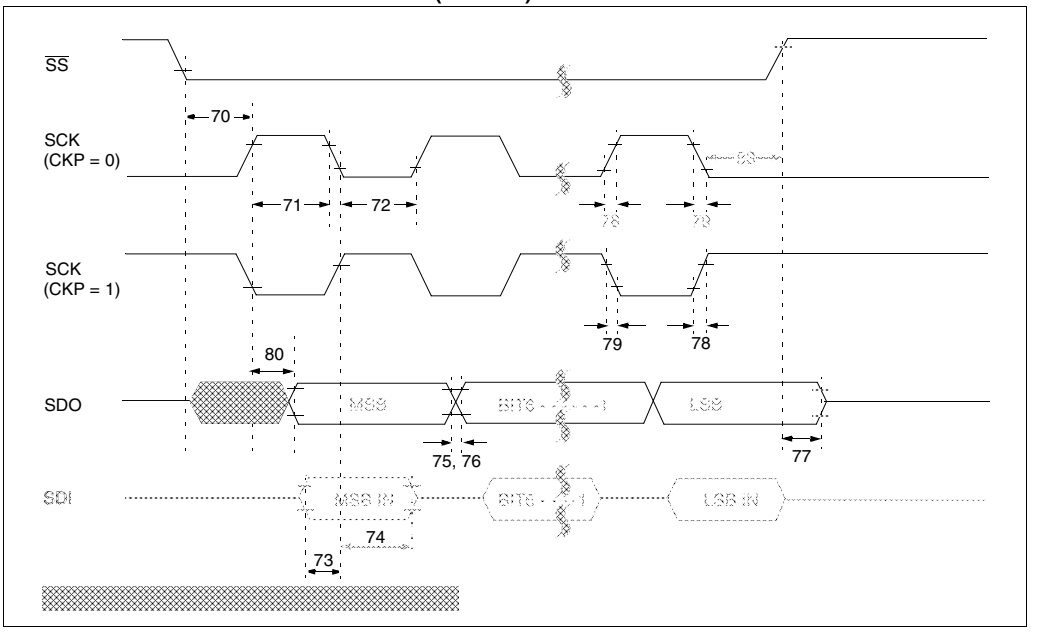
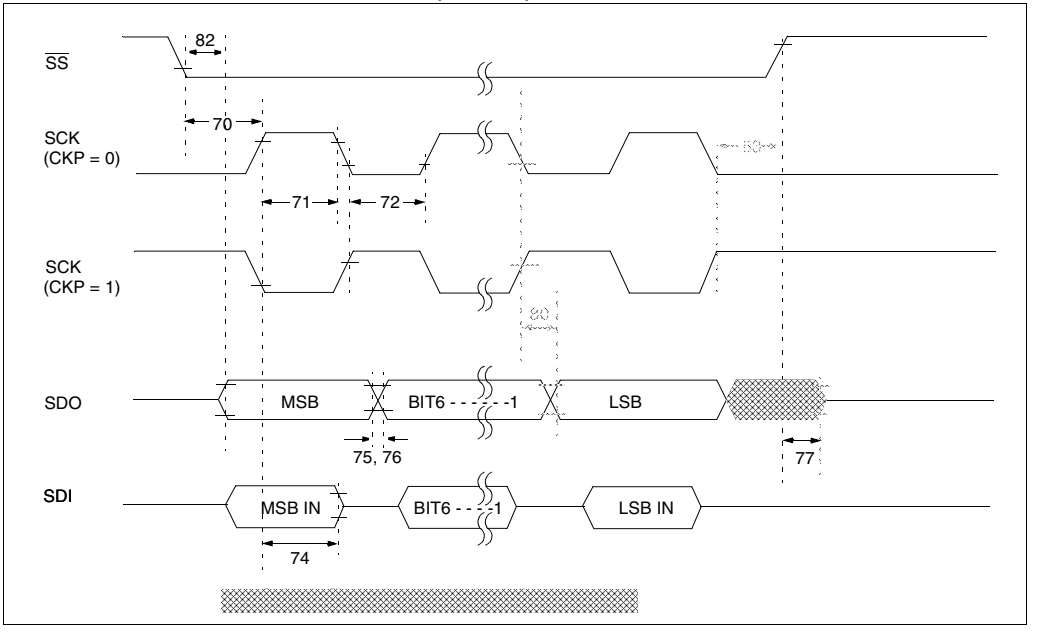


FIGURE 22-12: SPI SLAVE MODE TIMING (CKE = 1)



Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

TABLE 22-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK$\downarrow$ or SCK$\uparrow$ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge	TCY	—	—	ns	
82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge	—	—	50	ns	
83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge	1.5TCY + 40	—	—	ns	

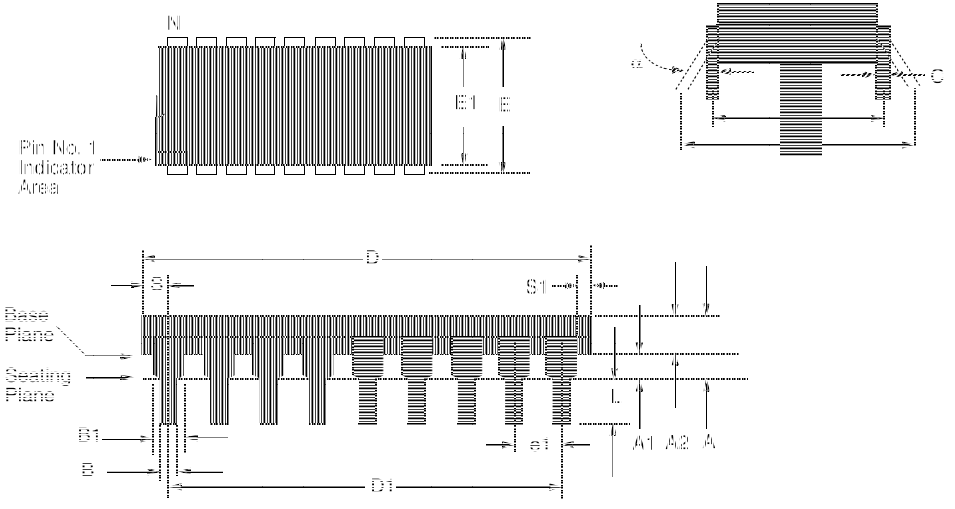
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

24.0 PACKAGING INFORMATION

24.1 18-Lead Plastic Dual In-line (300 mil) (P)

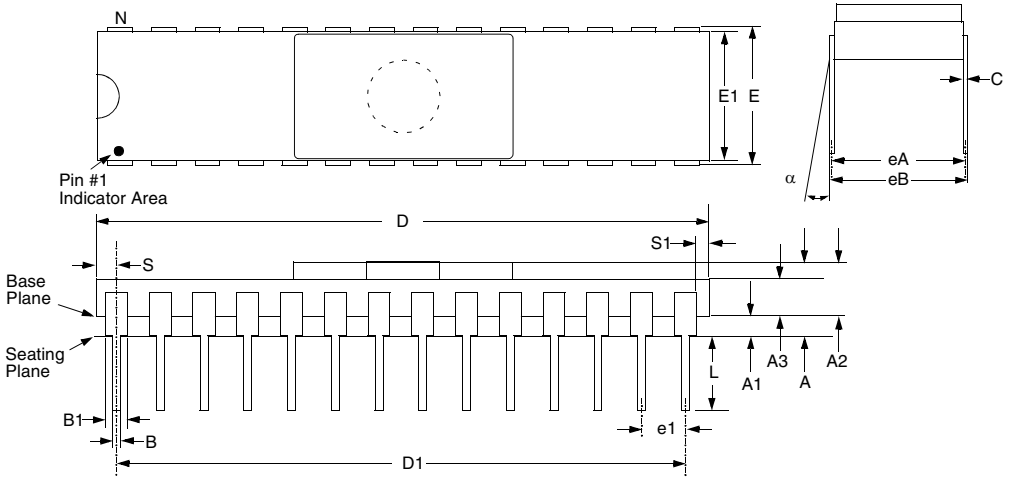
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Plastic Dual In-Line (PLA)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	–	4.064		–	0.160	
A1	0.381	–		0.015	–	
A2	3.048	3.810		0.120	0.150	
B	0.355	0.559		0.014	0.022	
B1	1.524	1.524	**Reference**	0.060	0.060	**Reference**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	22.479	23.495		0.885	0.925	
D1	20.320	20.320	**Reference**	0.800	0.800	**Reference**
E	7.620	8.255		0.300	0.325	
E1	6.096	7.112		0.240	0.280	
e1	2.489	2.591	**Typical**	0.098	0.102	**Typical**
eA	7.620	7.620	**Reference**	0.300	0.300	**Reference**
eB	7.874	9.906		0.310	0.390	
L	3.048	3.556		0.120	0.140	
N	18	18		18	18	
S	0.889	–		0.035	–	
S1	0.127	–		0.005	–	

24.9 28-Lead Ceramic Side Brazed Dual In-Line with Window (300 mil) (JW)

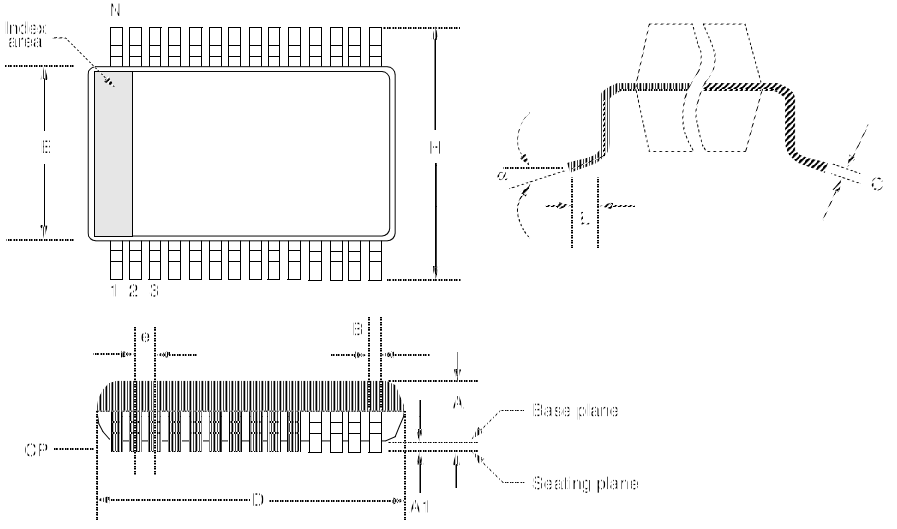
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Ceramic Side Brazed Dual In-Line (CER)						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	3.937	5.030		0.155	0.198	
A1	1.016	1.524		0.040	0.060	
A2	2.921	3.506		0.115	0.138	
A3	1.930	2.388		0.076	0.094	
B	0.406	0.508		0.016	0.020	
B1	1.219	1.321	**Typical**	0.048	0.052	
C	0.228	0.305	**Typical**	0.009	0.012	
D	35.204	35.916		1.386	1.414	
D1	32.893	33.147	**Reference**	1.295	1.305	
E	7.620	8.128		0.300	0.320	
E1	7.366	7.620		0.290	0.300	
e1	2.413	2.667	**Typical**	0.095	0.105	
eA	7.366	7.874	**Reference**	0.290	0.310	
eB	7.594	8.179		0.299	0.322	
L	3.302	4.064		0.130	0.160	
N	28	28		28	28	
S	1.143	1.397		0.045	0.055	
S1	0.533	0.737		0.021	0.029	

24.10 28-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Plastic SSOP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	1.730	1.990		0.068	0.078	
A1	0.050	0.210		0.002	0.008	
B	0.250	0.380		0.010	0.015	
C	0.130	0.220		0.005	0.009	
D	10.070	10.330		0.396	0.407	
E	5.200	5.380		0.205	0.212	
e	0.650	0.650	**Reference**	0.026	0.026	**Reference**
H	7.650	7.900		0.301	0.311	
L	0.550	0.950		0.022	0.037	
N	28	28		28	28	
CP	-	0.102		-	0.004	

F.10 PIC17CXXX Family of Devices

		PIC17C42A	PIC17CR42	PIC17C43	PIC17CR43	PIC17C44
Clock	Maximum Frequency of Operation (MHz)	33	33	33	33	33
Memory	EPROM Program Memory (words)	2K	—	4K	—	8K
	ROM Program Memory (words)	—	2K	—	4K	—
	RAM Data Memory (bytes)	232	232	454	454	454
Peripherals	Timer Module(s)	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3
	Captures/PWM Module(s)	2	2	2	2	2
	Serial Port(s) (USART)	Yes	Yes	Yes	Yes	Yes
Features	Hardware Multiply	Yes	Yes	Yes	Yes	Yes
	External Interrupts	Yes	Yes	Yes	Yes	Yes
	Interrupt Sources	11	11	11	11	11
	I/O Pins	33	33	33	33	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	Number of Instructions	58	58	58	58	58
	Packages	40-pin DIP; 44-pin PLCC, MQFP, TQFP	40-pin DIP; 44-pin PLCC, MQFP, TQFP	40-pin DIP; 44-pin PLCC, MQFP, TQFP	40-pin DIP; 44-pin PLCC, MQFP, TQFP	40-pin DIP; 44-pin PLCC, MQFP, TQFP

		PIC17C752	PIC17C756
Clock	Maximum Frequency of Operation (MHz)	33	33
Memory	EPROM Program Memory (words)	8K	16K
	ROM Program Memory (words)	—	—
	RAM Data Memory (bytes)	454	902
Peripherals	Timer Module(s)	TMR0, TMR1, TMR2, TMR3	TMR0, TMR1, TMR2, TMR3
	Captures/PWM Module(s)	4/3	4/3
	Serial Port(s) (USART)	2	2
Features	Hardware Multiply	Yes	Yes
	External Interrupts	Yes	Yes
	Interrupt Sources	18	18
	I/O Pins	50	50
	Voltage Range (Volts)	3.0-6.0	3.0-6.0
	Number of Instructions	58	58
	Packages	64-pin DIP; 68-pin LCC, 68-pin TQFP	64-pin DIP; 68-pin LCC, 68-pin TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.